ABSTRACT

Provided is a wafer processing method, comprising: rotating a wafer; supplying a processing liquid to the rotation center of the wafer through a nozzle, so as to form a localized liquid film on the surface of the wafer; before the localized liquid film diffuses to the edge of the wafer, moving the nozzle and continuously supplying the processing liquid, so that the liquid landing point of the processing liquid moves from the rotation center of the wafer to a first position. The wafer processing method of the present application can reduce liquid splashing.